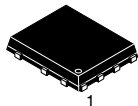


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

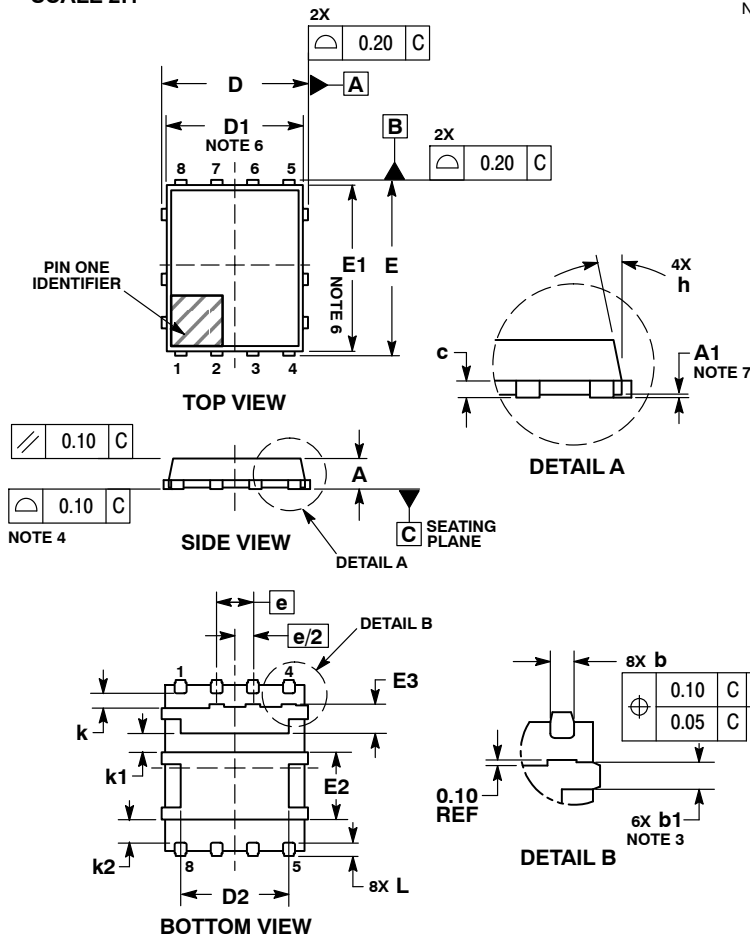


SCALE 2:1

DFN8 5x6, 1.27P Dual Flag (SO8FL-Dual-Asymmetrical)

CASE 506BX
ISSUE D

DATE 24 JUN 2014

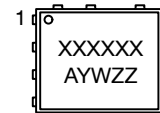


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
5. DIMENSIONS *b* AND *L* ARE MEASURED AT THE PACKAGE SURFACE.
6. DIMENSIONS *D1* AND *E1* DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
7. SEATING PLANE IS DEFINED BY THE TERMINALS. *A1* IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

MILLIMETERS		
DIM	MIN	MAX
A	0.90	1.10
A1	0.00	0.05
<i>b</i>	0.41	0.61
<i>b1</i>	0.41	0.61
<i>c</i>	0.23	0.33
D	5.00	5.30
D1	4.50	5.10
D2	3.50	4.22
E	6.00	6.30
E1	5.50	6.10
E2	2.27	2.67
E3	0.82	1.22
<i>e</i>	1.27 BSC	
<i>h</i>	---	12 °
<i>k</i>	0.39	0.59
<i>k1</i>	0.56	0.76
<i>k2</i>	0.73	0.93
<i>L</i>	0.35	0.55

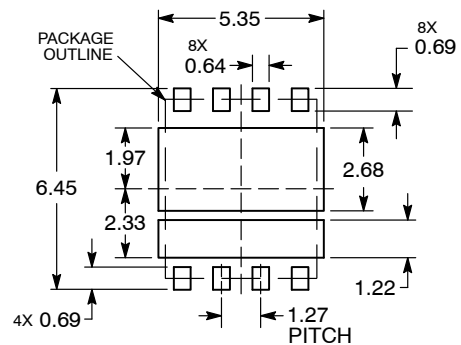
GENERIC MARKING DIAGRAM*



- XXXXXX= Specific Device Code
 A = Assembly Location
 Y = Year
 W = Work Week
 ZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSION: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLE 1:

- PIN 1. GATE 1
 2. DRAIN 1
 3. DRAIN 1
 4. DRAIN 1
 5. SOURCE 2
 6. SOURCE 2
 7. SOURCE 2
 8. GATE 2
 9. DRAIN 1
 10. SOURCE 1/DRAIN 2

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DESCRIPTION:	DFN8 5X6, 1.27P DUAL FLAG (SO8FL-DUAL-ASYMMETRICAL)	PAGE 1 OF 1

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